

IN THE SPECIFICATION:

Please AMEND paragraph [0042] as follows:

The photo resist may be made of a resin of a photosensitive epoxy group, a resin of a ~~polyimide~~polyimide group, or a resin of a polyacrylate group.

Please AMEND paragraph [0044] as follows:

The forming of the photo resist may include forming the photo resist to have a thickness from 10 μm to 100 μm . The forming of the photo resist may also include forming the photo resist with a resin of a photosensitive epoxy group, a resin of a ~~polyimide~~polyimide group, or a resin of a polyacrylate group.

Please AMEND paragraph [0057] as follows:

The chamber/nozzle plate 109 is made of any one of a resin of a photosensitive epoxy group such as SU-8 manufactured by MICROCHEM, a resin of a ~~polyimide~~polyimide group such as DURAMID manufactured by ARCHCHEM, or a resin of a polyacrylate group such as a negative dry film resist manufactured by TOK and JSR.